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Tokyo Eletech Corporation

Notes in handling LSPACK

1. LSPACK was developed for the emulation test or system development purpose only. Therefore, Electrical Appliance and Material Safety Law or EMI standards do not approve the adapter.
2. When LSPACK is taken out of a packing box, press the product lightly by a finger, and then remove the packing materials first. Check if pins are damaged.
3. While a packing box has been kept under ambient temperature higher than 50 ℃ for long time, the box might be deformed. The storage place should be free from sunlight, and room temperature should be 40℃ or lower.
4. Cleaning for DSPACK should not be done. The cleaning materials and flux will contaminate in DSPACK due to the construction of the adapter. Cleaning for DIP components should not be done with LSPACK since flux for soldering DIP components will penetrate into LSPACK through guide pinholes.
5. The screwdriver attached or a torque driver should be used for fixing the top cover on to the spacer of DSPACK. 4 screws should be loosely fastened first, then tightly fasten the screws with equal torque. Fastening torque should be 0.054N・m(0.55kgf・ cm) Max. Excess tightening torque for one screw only will cause poor contact.
6. Foreign materials and dusts on solder balls and, also oxidized solder balls will cause poor contact with pogo pin. Remove those before loading BGA package into the adapter.
7. Fixing screws and nuts for the top cover and PWB should be loosened while an emulation device is kept in a shelf for long time.
8. LSPACK should be used together with CSSOCKET and BSSOCKET for emulation test purpose only.
9. LSPACK cannot withstand under vibration or shock environment.

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